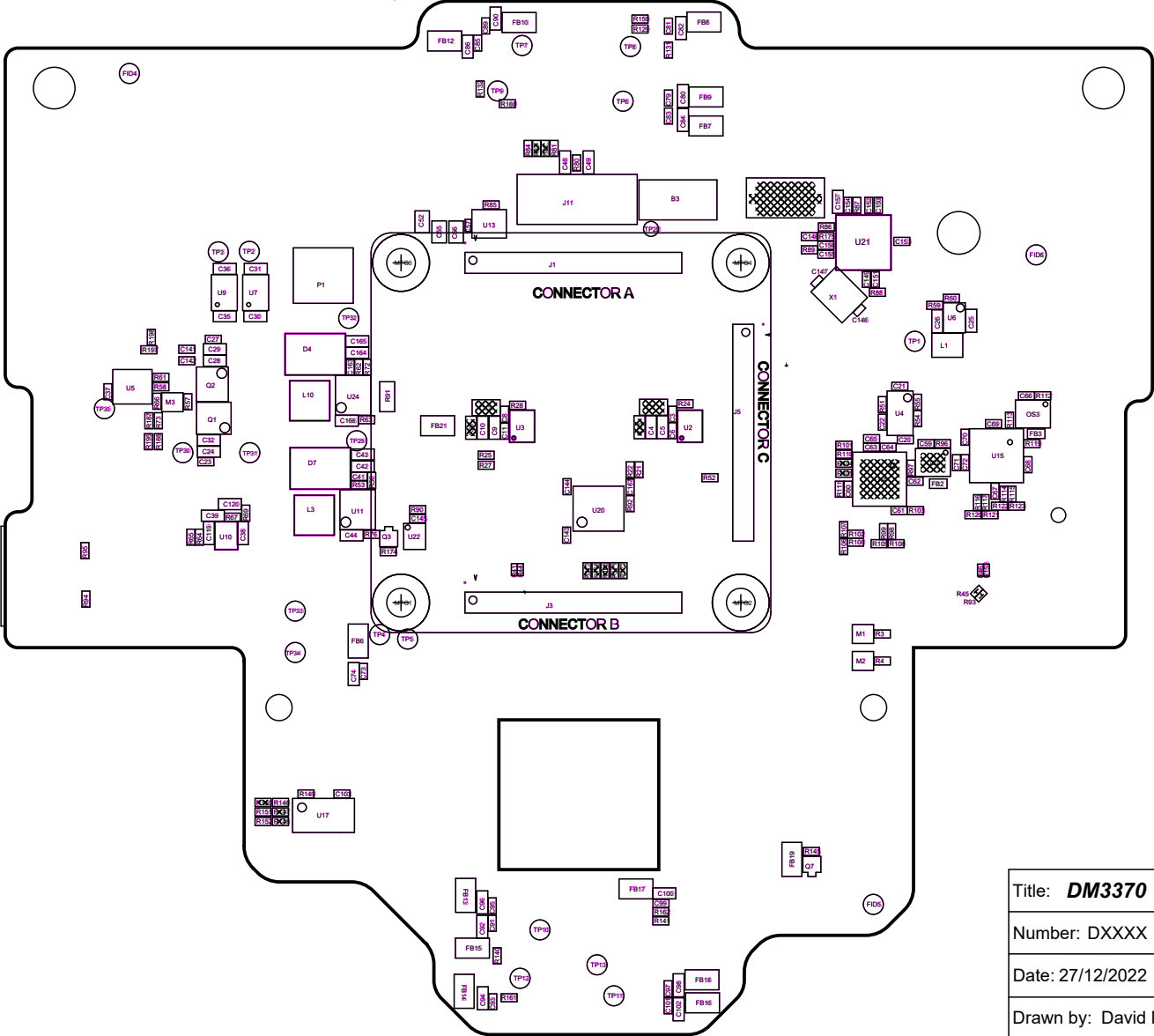


ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.  
Assembly shall conform with RoHS Directive 2011/65/EU.  
Components shall be placed according to the associated CPL and BOM documents.  
Lead-free SAC305 solder shall be used.  
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.  
BGA components shall be 100% checked with x-ray for solder bridges after reflow.  
Finished assemblies shall be removed from panel prior to delivery.

[Variant: Production] View from Top side (Scale 1.5:1)



A

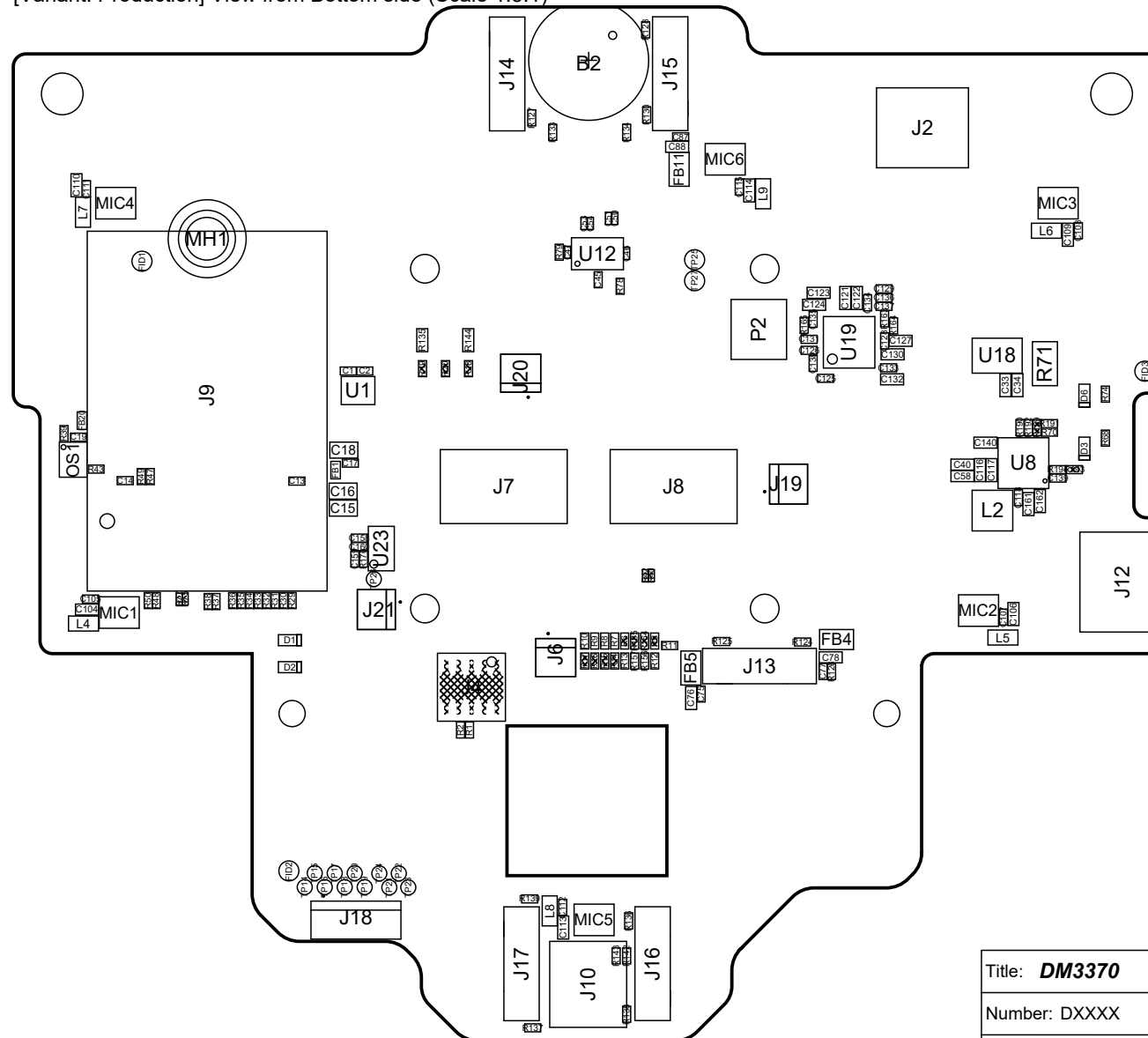
B


C

D

E

[Variant: Production] View from Bottom side (Scale 1.5:1)



Title: <b>DM3370</b>		
Number: DXXXX	Revision: R1M1E2	
Date: 27/12/2022	Sheet: 2 of 2	PROPRIETARY AND CONFIDENTIAL
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